

IN THE CLAIMS:

1. (Currently Amended) A manufacturing method of a display device comprising including the step of:

forming a wiring by partially forming etching a conductor film over a substrate by use of discharging a reactive gas from a plasma treatment means having one set of electrodes ~~an electrode~~ for generating plasma at a pressure of 5 to 800 Torr.

2. (Currently Amended) A manufacturing method of a display device comprising including the step of:

forming a wiring by partially forming etching a conductor film over a substrate by use of discharging a reactive gas from a plasma treatment means having a plurality of sets of electrodes for generating plasma at a pressure of 5 to 800 Torr.

3. (Canceled)

4. (Currently Amended) A manufacturing method of a display device comprising the steps of:

~~partially forming a conductor film over a substrate at a pressure of 5 to 800 Torr by use of first plasma treatment means having a plurality of electrodes;~~

forming a resist mask over [[on]] the conductor film; and

~~partially etching the conductor film at a pressure of 5 to 800 Torr by use of discharging a reactive gas from a second plasma treatment means having one set of electrodes with the resist mask as a mask and forming a wiring.~~

5. (Currently Amended) A manufacturing method of a display device comprising the steps of:

~~partially forming a conductor film over a substrate at a pressure of 5 to 800 Torr by use of first plasma treatment means;~~

forming a resist mask over [[on]] the conductor film; and

partially etching the conductor film at a pressure of 5 to 800 Torr by ~~use of~~ ~~discharging a reactive gas from a second~~ plasma treatment means having a plurality of sets of electrodes with the resist mask as a mask and forming a wiring.

6. (Currently Amended) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5 4-to-5, wherein the substrate has a size of 1,000 x 1,200 mm² or more.

7. (Currently Amended) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5 4-to-5, wherein the plasma treatment means scans the substrate in one direction.

8. (Currently Amended) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5 4-to-5, wherein the plasma treatment means alternately scans the substrate in a row direction and in a column direction.

9. (Currently Amended) The manufacturing method of the display device according to any of claims 4 and 5 3-to-5, wherein the resist mask is formed by use of liquid droplet jetting means.

10. – 11. (Canceled)